

SV-SMT 7.62HP/02/90SF 2.6SN BK BX
Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com
Product image


Similar to illustration

OMNIMATE Power BV / SV 7.62HP – the 28 kVA performance class
Tailor-made solutions for high performers

More power reserves for higher load bearing capacity: The OMNIMATE Power BV / SV 7.62HP is the middle-class of the power connector systems. It has a large clamping capacity, high overload resistance and the largest range of variants and accessories to choose from: the high performer of the HP range. HP means High Performance – this performance covers a great deal: the full rated current up to 50°C without derating, unlimited 600-V approval according to UL, and the additional finger safety for 400 V-TN systems (+ 3.0 mm) in compliance with the application directive IEC 61800-5-1.

General ordering data

Version	PCB plug-in connector, male header, Screw flange, THT/THR solder connection, 7.62 mm, Number of poles: 2, 90°, Solder pin length (l): 2.6 mm, tinned, black, Box
Order No.	2499600000
Type	SV-SMT 7.62HP/02/90SF 2.6SN BK BX
GTIN (EAN)	4050118513011
Qty.	60 pc(s).
Product data	IEC: 1000 V / 41 A UL: 300 V / 40.5 A
Packaging	Box

Creation date April 15, 2021 10:48:09 PM CEST

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Technical data

Dimensions and weights

Depth	28.3 mm	Depth (inches)	1.114 inch
Height of lowest version	11.4 mm	Net weight	4.4 g

System specifications

Product family	OMNIMATE Power - series BV/SV 7.62HP	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	7.62 mm
Pitch in inches (P)	0.3 inch	Outgoing elbow	90°
Number of poles	2	Number of solder pins per pole	2
Solder pin length (l)	2.6 mm	Solder pin length tolerance	+0.1 / -0.3 mm
Solder pin dimensions	0.8 x 1.0 mm	Solder eyelet hole diameter (D)	1.4 mm
Solder eyelet hole diameter tolerance (D)+	0.1 mm	L1 in mm	22.86 mm
L1 in inches	0.9 inch	Number of rows	1
Pin series quantity	1	Touch-safe protection acc. to DIN VDE 57 106	safe to back of hand above the printed circuit board
Touch-safe protection acc. to DIN VDE 0470	IP 20	Volume resistance	2.00 mΩ
Tightening torque for screw flange, min.	0.2 Nm	Tightening torque for screw flange, max.	0.3 Nm
Plugging cycles	25	Plugging force/pole, max.	12 N
Pulling force/pole, max.	7 N		

Material data

Insulating material	PA GF HT3	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	I
Comparative Tracking Index (CTI)	≥ 600	Insulation strength	≥ 10 ⁸ Ω
Moisture Level (MSL)	3	UL 94 flammability rating	V-0
Contact material	Copper alloy	Contact surface	tinned
Layer structure of solder connection	1...3 µm Ni / 4...6 µm Sn matt	Layer structure of plug contact	1...3 µm Ni / 4...6 µm Sn matt
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-50 °C	Operating temperature, max.	130 °C
Temperature range, installation, min.	-25 °C	Temperature range, installation, max.	130 °C

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	41 A
Rated current, max. number of poles (Tu=20°C)	41 A	Rated current, min. number of poles (Tu=40°C)	41 A
Rated current, max. number of poles (Tu=40°C)	41 A	Rated voltage for surge voltage class / pollution degree II/2	1,000 V
Rated voltage for surge voltage class / pollution degree III/2	630 V	Rated voltage for surge voltage class / pollution degree III/3	630 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	6 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	6 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	6 kV	Short-time withstand current resistance	3 x 1s with 420 A

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Technical data

Rated data acc. to UL 1059

Institute (cURus)



Certificate No. (cURus)

E60693

Rated voltage (Use group B / UL 1059) 300 V

Rated voltage (Use group D / UL 1059) 300 V

Rated current (Use group C / UL 1059) 40.5 A

Clearance distance, min. 6.9 mm

Reference to approval values Specifications are maximum values, details - see approval certificate.

Rated voltage (Use group C / UL 1059) 300 V

Rated current (Use group B / UL 1059) 40.5 A

Rated current (Use group D / UL 1059) 10 A

Creepage distance, min. 9.6 mm

Packing

Packaging	Box	VPE length	338 mm
VPE width	130 mm	VPE height	33 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01

Important note

IPC conformity Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Notes

- Additional colours on request
- Rated current related to rated cross-section & min. No. of poles.
- P on drawing = pitch
- Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

Approvals



UL File Number Search E60693

Downloads

Brochure/Catalogue [Catalogues in PDF-format](#)

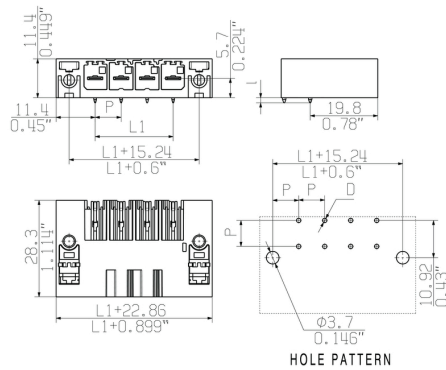
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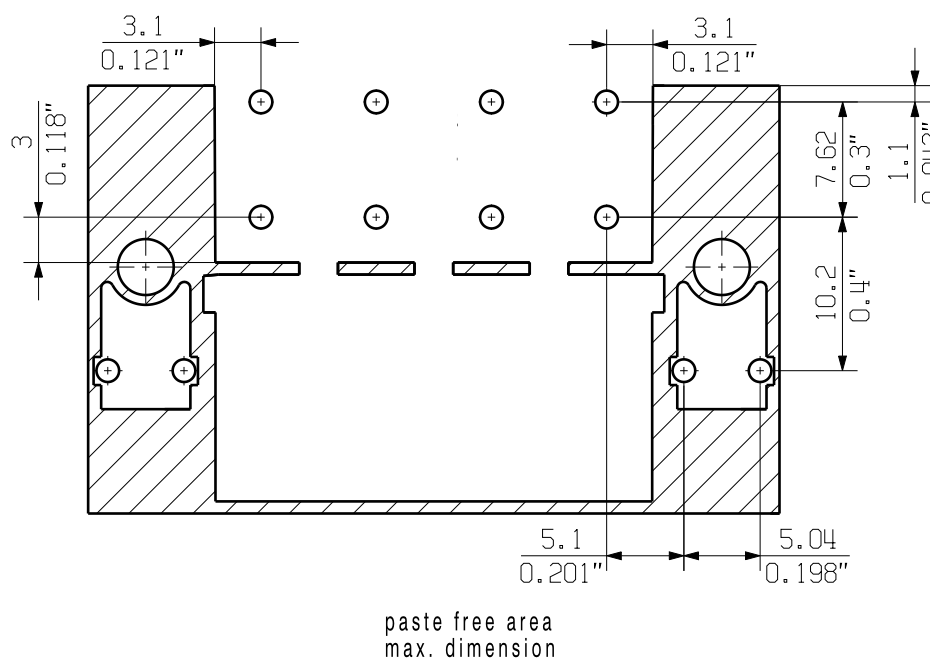
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Drawings

Dimensional drawing

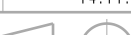


Lötstifte nur für MLF-Varianten
Soldering pins only for MLF-variants



A perspective view of a multi-chambered microfluidic device. It features a central row of five chambers, each with a central inlet and outlet. On the left and right sides, there are larger circular ports, likely for sample or reagent addition. The device is shown in a perspective view, highlighting its three-dimensional structure.

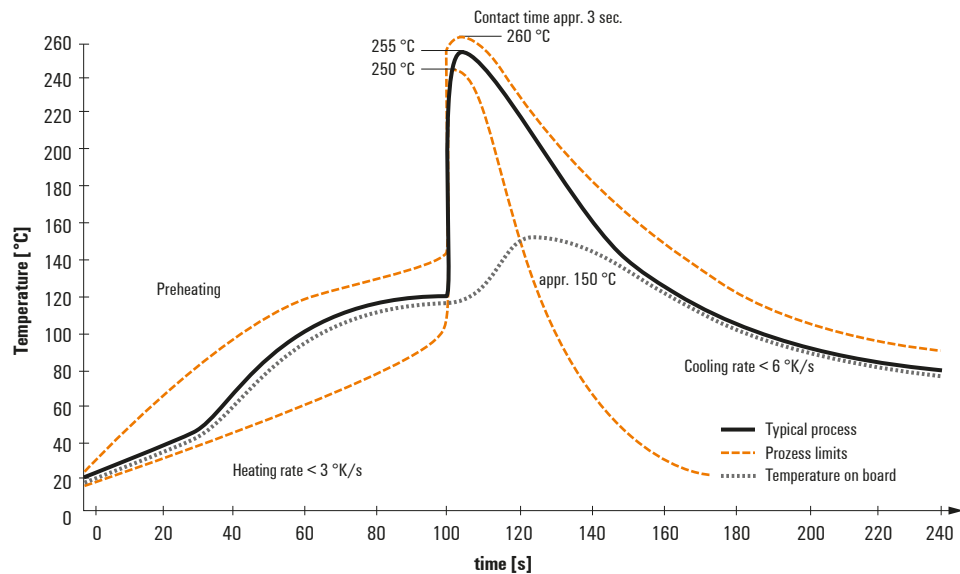
1.5
2.6
3.5
l [mm]

RoHS COMPLIANT		EC00002212	Prim PLM Part No.: 225880		Prim ERP Part No.: 2499550000	
First Issue Date		Max. nos.	Weidmüller		63450	
14.11.2016		Modification			Drawing no. _____ Issue no. _____	
		Date	Name	SV-SMT 7.62HP/IT../90/270... STISTLEISTE MALE HEADER		
	Drawn	30.08.2019	Helis, Maria			
	Responsible		Döhner, Karl			
	Approved	09.10.2019	Lang, Thomas			
Scale: 2:1		Size: A2		Product file: 7407 BLF 7.50HP		
Drawings Assembly						

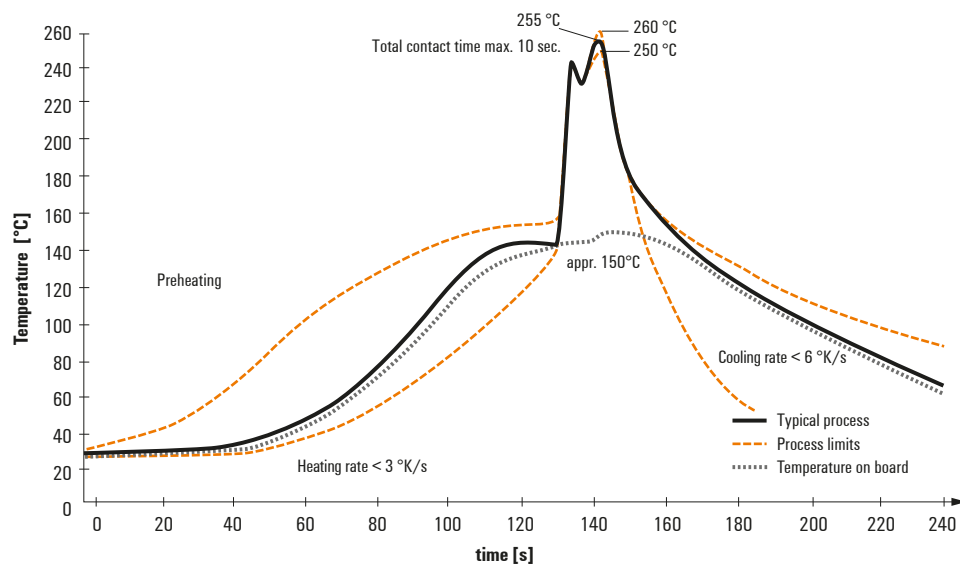
Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

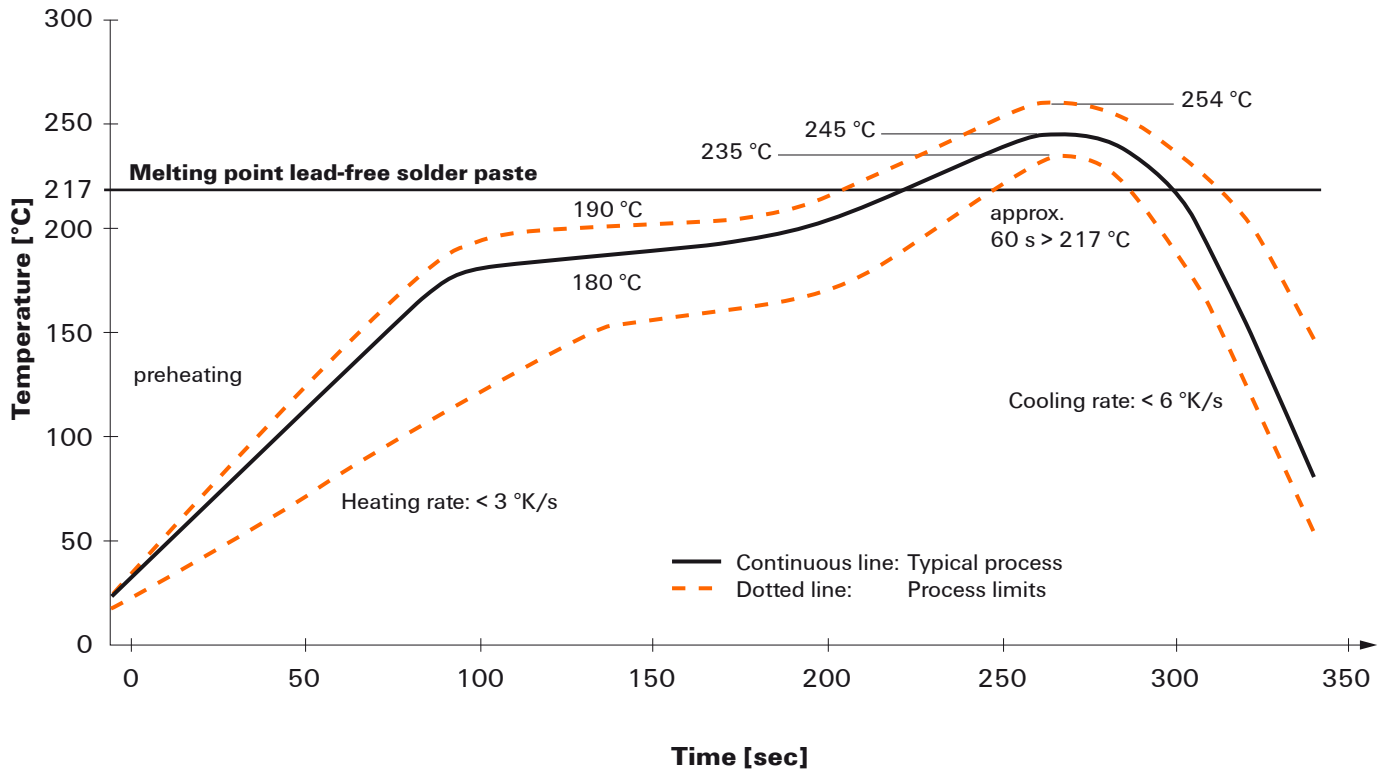
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.